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PATENTS OF



103549243

To the Director of the U.S. Patent and Trademark Office: Please record.

30212

1. Name of conveying party(ies):  
Chang-Hee Shin (02/03/2009), Ki-Seok Cho  
(02/03/2009), and Seong-Do Jeon (02/03/2009)  
Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)  
Name: MagnaChip Semiconductor, Ltd.  
Internal Address: \_\_\_\_\_  
Street Address: \_\_\_\_\_

3. Nature of conveyance/Execution Date(s):  
Execution Date(s): in parentheses after inventor name  
 Assignment  Merger  Change of Name  
 Security Agreement  Joint Research Agreement  
 Government Interest Assignment  
 Executive Order 9424, Confirmatory License  
 Other \_\_\_\_\_

1 Hyangjeong-dong, Heungduk-gu,  
City: Cheongju-Si  
State: Chungcheongbuk-do  
Country: Republic of Korea Zip: 361-725  
Additional name(s) & address(es) attached?  Yes  No

4. Application or patent number(s):  
A. Patent Application No.(s)  
Additional numbers attached?  Yes  No

This document is being filed together with a new application.  
B. Patent No.(s)  
 Yes  No

5. Name and address to whom correspondence concerning document should be mailed:  
Name: Collin W. Park  
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6. Total number of applications and patents involved: 1  
7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00  
 Authorized to be charged to deposit account  
 Enclosed  
 None required (government interest not affecting title)

8. Payment Information  
Deposit Account Number 50-0310  
Authorized User Name Robert J. Goodell

9. Signature:   
Signature Robert J. Goodell - 41,040 Date February 12, 2009  
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 2

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**ASSIGNMENT**

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

**ANTI-FUSE AND METHOD FOR FORMING THE SAME, UNIT CELL OF  
 NON VOLATILE MEMORY DEVICE WITH THE SAME**

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on \_\_\_\_\_, (Serial No. \_\_\_\_\_); and




WHEREAS, MagnaChip Semiconductor, Ltd., a corporation of Republic of Korea, whose post office address is 1 Hyangjeong-dong, Heungduk-gu, Cheongju-si, Chungcheongbuk-do, 361-725, Republic of Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. \_\_\_\_\_, filed 12 FEB 2009) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor <b>SHIN, Chang-Hee</b>	Assignor's Signature 	Date February 3, 2009
Address: 1 Hyangjeong-dong, Heungduk-gu, Cheongju-si, Chungcheongbuk-do, 361-725, Republic of Korea		Citizenship Republic of Korea
Full Name of Second Assignor <b>CHO, Ki-Seok</b>	Assignor's Signature 	Date February 3, 2009
Address: 1 Hyangjeong-dong, Heungduk-gu, Cheongju-si, Chungcheongbuk-do, 361-725, Republic of Korea		Citizenship Republic of Korea
Full Name of Third Assignor <b>JEON, Seong-Do</b>	Assignor's Signature 	Date February 3, 2009
Address: 1 Hyangjeong-dong, Heungduk-gu, Cheongju-si, Chungcheongbuk-do, 361-725, Republic of Korea		Citizenship Republic of Korea
Full Name of Fourth Assignor	Assignor's Signature	Date
Address		Citizenship
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		

Morgan, Lewis & Bockius LLP